



UC1573
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Buck Pulse Width Modulator Stepdown Voltage Regulator

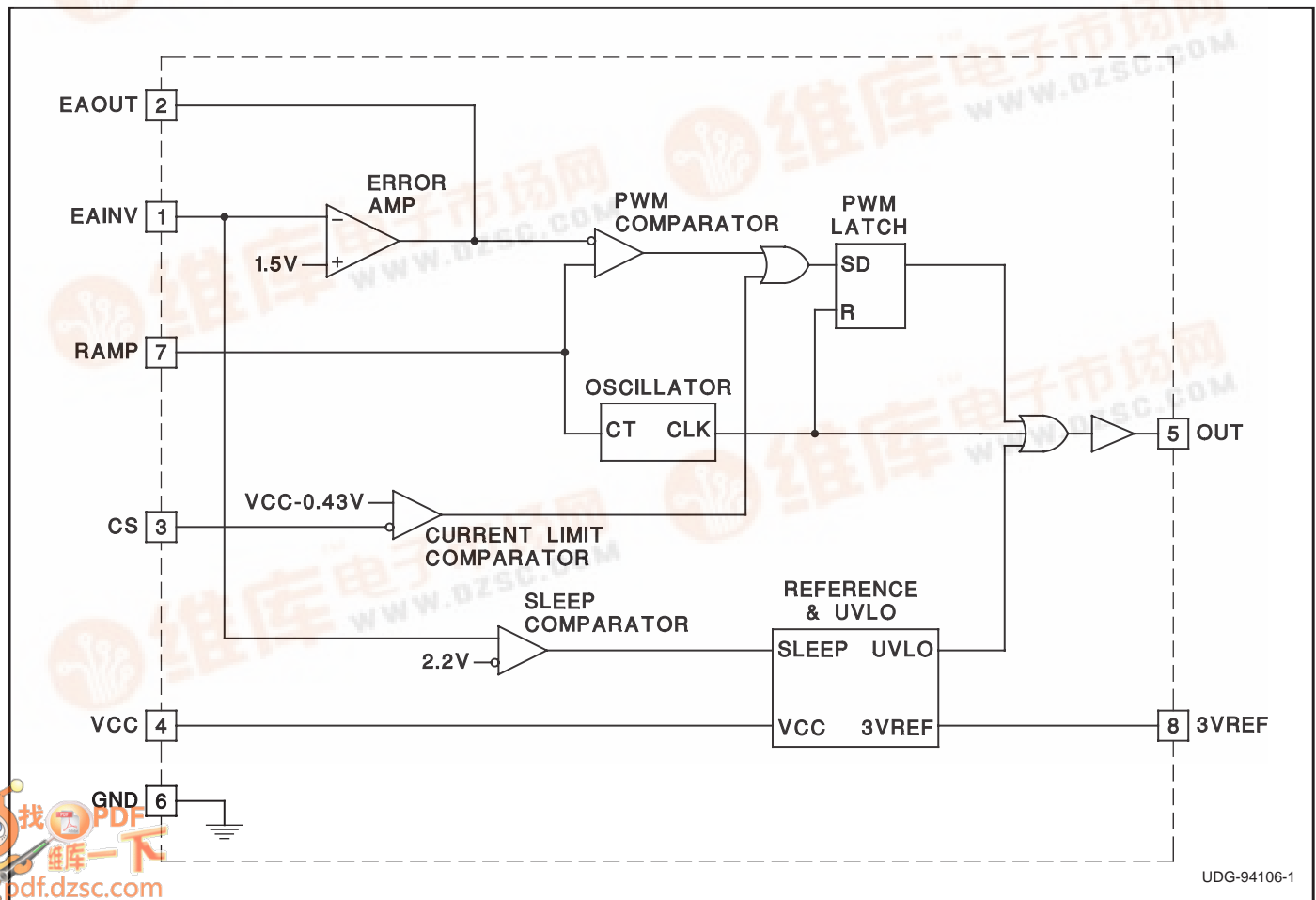
FEATURES

- Simple Single Inductor Buck PWM Stepdown Voltage Regulation
- Drives External PMOS Switch
- Contains UVLO Circuit
- Includes Pulse-by-Pulse Current Limit
- Low 50 μ A Sleep Mode Current

DESCRIPTION

The UC3573 is a Buck pulse width modulator which steps down and regulates a positive input voltage. The chip is optimized for use in a single inductor buck switching converter employing an external PMOS switch. The block diagram consists of a precision reference, an error amplifier configured for voltage mode operation, an oscillator, a PWM comparator with latching logic, and a 0.5A peak gate driver. The UC3573 includes an undervoltage lockout circuit to insure sufficient input supply voltage is present before any switching activity can occur, and a pulse-by-pulse current limit. Input current can be sensed and limited to a user determined maximum value. In addition, a sleep comparator interfaces to the UVLO circuit which turns the chip off when the input voltage is below the UVLO threshold. This reduces the supply current to only 50 μ A, making the UC3573 ideal for battery powered applications.

BLOCK DIAGRAM



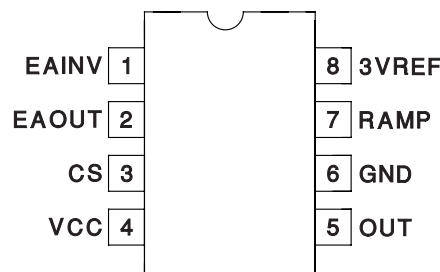
ABSOLUTE MAXIMUM RATINGS

VCC	35V
EAINV	−0.6V to VCC
IEAOUT	25mA
RAMP	−0.3V to 4V
CS	−0.3V to VCC
IO _{UT}	−0.7A to 0.7A
I _{3VREF}	−15mA
Storage Temperature	−65°C to +150°C
Junction Temperature	−65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C

Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

CONNECTION DIAGRAMS

DIL-8, SOIC-8 (TOP VIEW)
J or N, D Packages



ELECTRICAL CHARACTERISTICS: Unless otherwise specified, these parameters apply for $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$ for the UC1573, -40°C to $+85^\circ\text{C}$ for the UC2573, and 0°C to $+70^\circ\text{C}$ for the UC3573, $V_{CC} = 5\text{V}$, $C_T = 680\text{pF}$, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Reference Section					
3VREF		2.94	3	3.06	V
Line Regulation	$V_{CC} = 4.75$ to 30V		1	10	mV
Load Regulation	$I_{3VREF} = 0$ to -5mA		1	10	mV
Oscillator Section					
Frequency	$V_{CC} = 5\text{V}, 30\text{V}$	85	100	115	kHz
Error Amp Section					
EAINV	EAOUT = 2V	1.45	1.5	1.55	V
IEAINV	EAOUT = 2V		−0.2	−1	μA
AVOL	EAOUT = 0.5V to 3V	65	90		dB
EAOUT High	EAINV = 1.4V	3.6	4	4.4	V
EAOUT Low	EAINV = 1.6V		0.1	0.2	V
IEAOUT	EAINV = 1.4V , EAOUT = 2V	−350	−500		μA
	EAINV = 1.6V , EAOUT = 2V	7	20		mA
Unity Gain Bandwidth	$T_J = 25^\circ\text{C}$, $F = 10\text{kHz}$	0.6	1		MHz
Current Sense Comparator Section					
Threshold (referred to VCC)		−0.39	−0.43	−0.47	V
Input Bias Current	CS = VCC		150	800	nA
CS Propagation Delay			400		ns
Gate Drive Output Section					
OUT High Saturation	$I_{OUT} = 0$		0	0.3	V
	$I_{OUT} = -10\text{mA}$		0.7	1.5	V
	$I_{OUT} = -100\text{mA}$		1.5	2.5	V
OUT Low Saturation	$I_{OUT} = 10\text{mA}$		0.1	0.4	V
	$I_{OUT} = 100\text{mA}$		1.5	2.2	V
Rise Time	$T_J = 25^\circ\text{C}$, $C_{LOAD} = 1\text{nF} + 3.3\text{ Ohms}$		30	80	ns
Fall Time	$T_J = 25^\circ\text{C}$, $C_{LOAD} = 1\text{nF} + 3.3\text{ Ohms}$		30	80	ns
Pulse Width Modulator Section					
Maximum Duty Cycle	EAINV = 1.4V		92	96	%
Minimum Duty Cycle	EAINV = 1.6V			0	%
Modulator Gain	EAOUT = 1.5V to 2.5V	25	35	45	%/V
Undervoltage Lockout Section					
Start Threshold		3.5	4.2	4.5	V
Hysteresis		100	200	300	mV

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PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Sleep Mode Section					
Threshold		1.8	2.2	2.6	V
Supply Current Section					
I_{VCC}	$V_{CC} = 30\text{V}$		9	12	mA
I_{VCC}	$V_{CC} = 30\text{V}$, $EAINV = 3\text{V}$		50	150	μA

PIN DESCRIPTIONS

3VREF: Precision 3V reference. Bypass with 100nF capacitor.

CS: Peak current limit sense pin. Senses the current across a current sense resistor placed between V_{CC} and source of the PMOS Buck switch. OUT will be held high (PMOS buck switch off) if $V_{CC} - CS$ exceeds 0.4V.

EAINV: Inverting input to error amplifier. VOUT sense feedback connected to this pin. The non-inverting input of the error amplifier is internally connected to:

$$\frac{3VREF}{2} \text{ Volts.}$$

Connecting the EAINV pin to an external voltage greater than 2.6V commands the chip to go into a low current sleep mode.

EAOUT: Output of error amplifier. Use EAOUT and EAINV for loop compensation components.

GND: Circuit Ground.

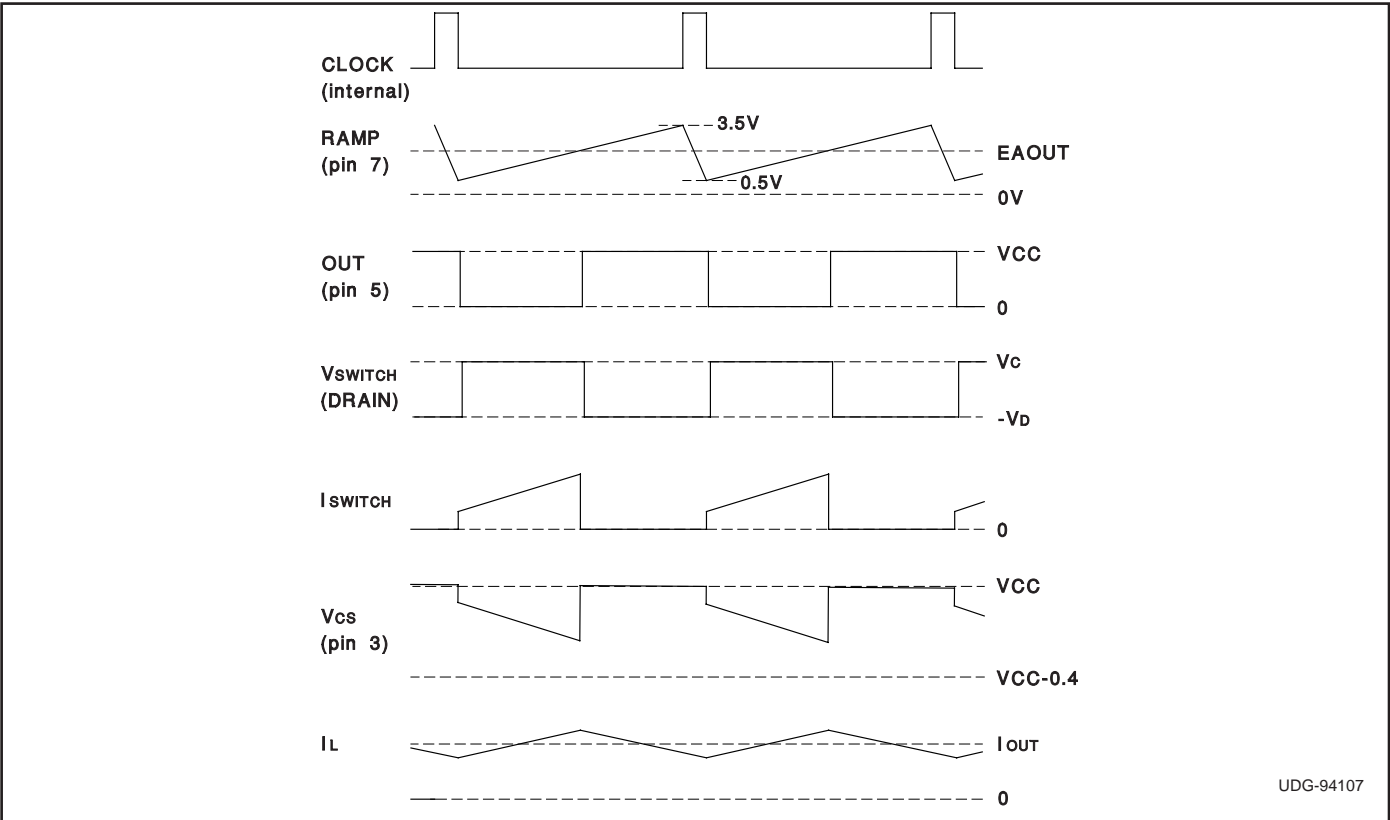
OUT: Gate drive for external PMOS switch connected between V_{CC} and the flyback inductor. OUT drives the gate of the PMOS switch between V_{CC} and GND.

RAMP: Oscillator and ramp for pulse width modulator. Frequency is set by a capacitor to GND by the equation

$$F = \frac{1}{15k \cdot C_{RAMP}}$$

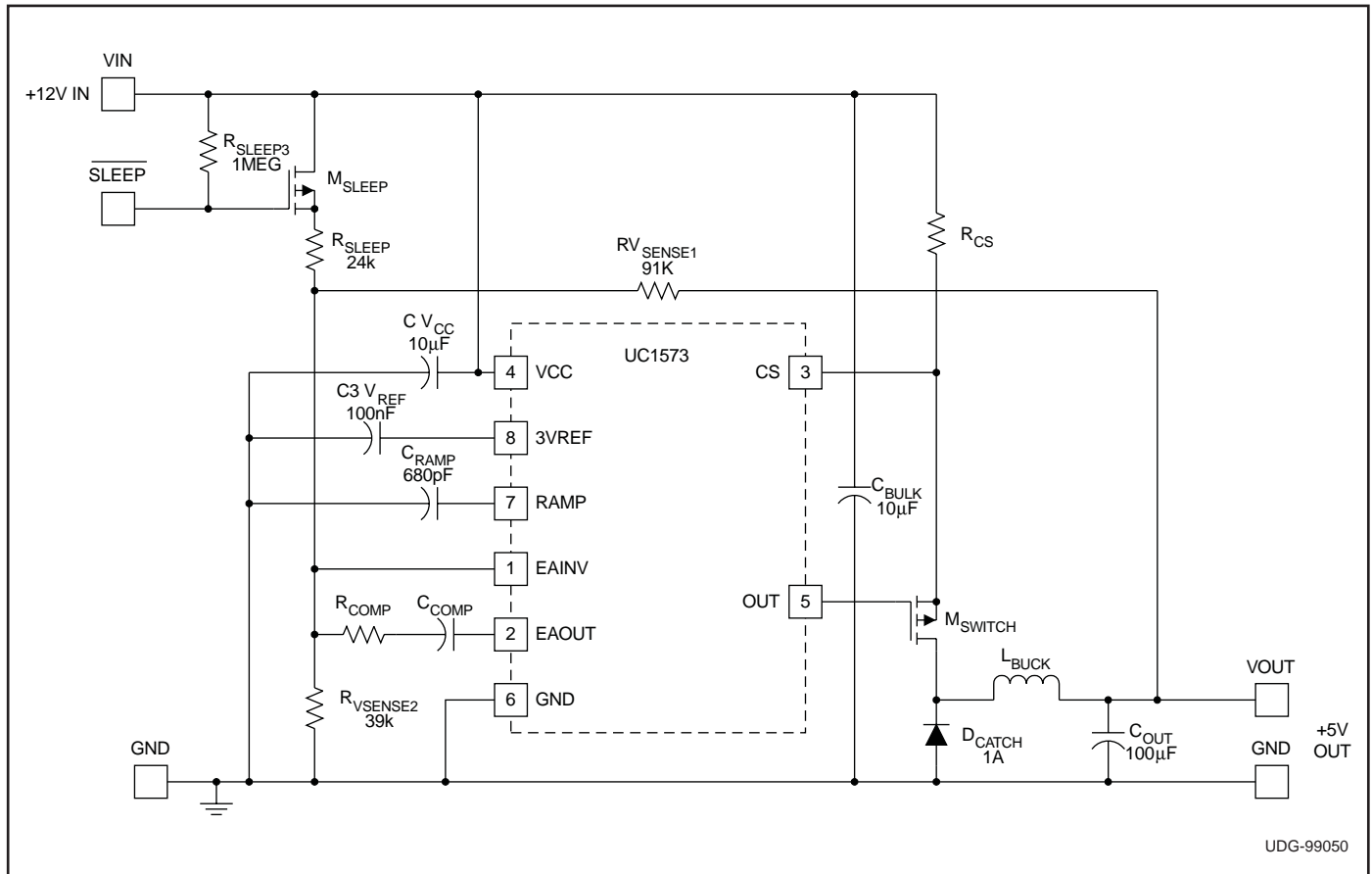
Recommended operating frequency range is 10kHz to 200kHz.

VCC: Input voltage supply to chip. Range is 4.75V to 30V. Bypass with a 1 μF capacitor.



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TYPICAL APPLICATION: 12V TO 5V BUCK CONVERTER



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